



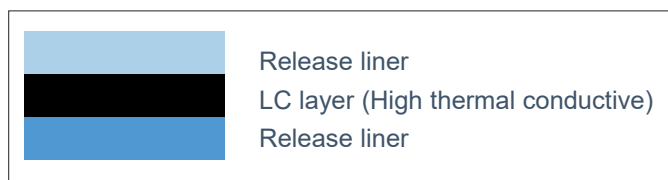
LINTEC Corporation *Linking your dreams*

PRODUCT NOVELTY

Thermal Conductive
Backside Coating Tape

PRODUCT NOVELTY

Designed to meet the demanding requirements of modern semiconductor manufacturing, **LINTEC's new advanced backside coating tape features a highly thermally conductive core that delivers outstanding thermal management and improved process efficiency.**



Tape structure

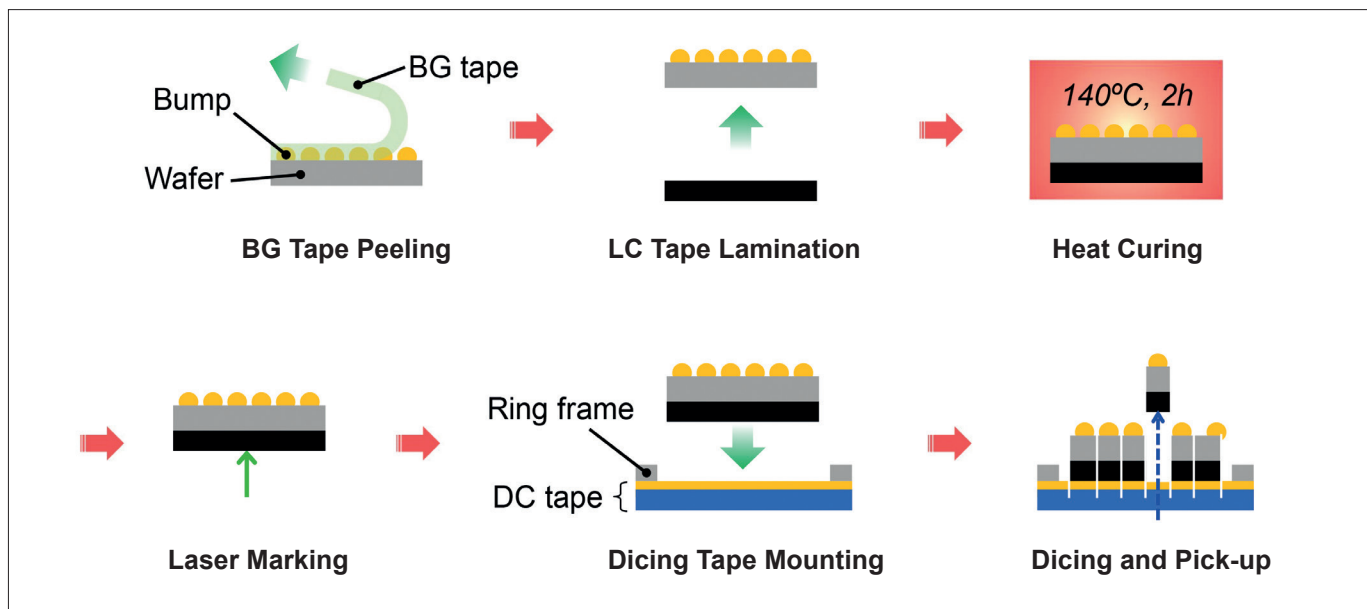
With a high thermal conductivity of 3 W/m·K, the tape efficiently dissipates heat generated by the device through the backside of the die. This helps improve heat management, enhances device reliability, and ensures stable performance even under demanding thermal conditions.

The tape is optimized for seamless integration into existing production lines and enables highly efficient lamination when used with the **LC Tape Laminator RAD-3600F/12**. This ensures consistent application quality and supports high-throughput manufacturing processes.

The solution is specifically designed for power ICs used in high-current applications, particularly in industries where thermal performance is critical. Typical applications include industrial equipment such as factory automation systems, robotics, and industrial power supplies, automotive applications, energy systems such as residential battery storage inverters, as well as telecommunications, servers, and data centre power supplies.

The tape is especially suitable for power devices. In high-current power devices, power loss and heat generation increase rapidly as current levels rise, making efficient heat dissipation essential for maintaining performance, reliability, and long-term operational stability.

PROCESS FLOW OF NEW LC TAPE



SPECIFICATION

Tape (25μm)	LC2850 (25)	LC72-25 TEST5 <i>Development</i>	Remarks
Color	Black	Black	—
Thermal conductivity (W/m·K)	0.3	3.0	Measured by cyclic heat method ISO22007-3
Transmittance (%)	0.1	< 0.1	Wavelength range: 1300 nm
Weight loss (%)	1.1	0.7	Measured by TG-DTA
CTE α2 (ppm/K)	110	70	Measured by TMA
Adhesion (mN/10mm)	5,300	11,000	Cu foil / Back side coating layer / Si wafer (#2000)
Wafer warpage (mm)	< 0.5	< 0.5	8 inch wafer / 280 μm thickness
MSL	Level1	Level1	IR reflow: 260°C / 3 times
TCT	Condition G	Condition C	JEDEC STANDARD (JESD22-A104-B) Condition G: -40°C⇔125°C x 1000 cycles Condition C: -65°C⇔150°C x 1000 cycles

Heat curing condition: 130°C/2hr (LC2850(25), 140°C/2hr (LC72-25 TEST5 (Development))

The indicated values are measured values and not intended for guarantee use.

ADVANTAGES

- Excellent heat dissipation for enhanced device performance
- High thermal conductivity: 3 W/m·K
- Reliable and uniform backside coverage
- Efficient application with RAD-3600F/12 (compatible with roll-type LC-tape), RAD-2510F/12Sa, RAD-2510F/8 and RAD-2500m-Series (all compatible with pre-cut LC-tape)
- Suitable for advanced semiconductor processes



Contact us.
We look forward to
meeting you!



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